PCA9306-Q1 双路双向 I²C 总线和 SMBus 电压电平转换器

1 特性

- 符合面向汽车应用的 AEC-Q100 标准
  - 温度等级 2：–40°C 至 105°C，T_A
  - HBM ESD 分类等级 H2
  - CDM ESD 分类等级 C4B
- 适用于混合模式 I²C 应用中 SDA 和 SCL 线路的 2 位双向转换器
- 与 I²C 和 SMBus 兼容
- 小于 1.5ns 的最大传播延迟，适应标准模式和快速模式 I²C 器件和多个控制器
- 可实现以下电压之间的电压电平转换
  - 1.2V V_{REF1} 和 1.8V、2.5V、3.3V 或 5V V_{REF2}
  - 1.8V V_{REF1} 和 2.5V、3.3V 或 5V V_{REF2}
  - 2.5V V_{REF1} 和 3.3V 或 5V V_{REF2}
  - 3.3V V_{REF1} 和 5V V_{REF2}
- 在无方向引脚的情况下提供双向电压转换
- 输入和输出端口之间 3.5Ω 的低导通状态连接提供更少的信号失真
- 漏极开路 I²C I/O 端口（SCL1、SDA1、SCL2 和 SDA2）
- 5V 耐压 I²C I/O 端口支持混合模式信号操作
- 针对 EN 为低电平的高阻抗 SCL1、SDA1、SCL2 和 SDA2 引脚
- 无闭锁操作可在 EN 为低电平时实现隔离
- 采用直通引脚排列以简化印刷电路板布线
- 闩锁性能超过 100mA，符合 JESD 78 II 类规范的要求
- ESD 保护性能超过 JESD 22 规范要求
  - 2000V 人体放电模型 (A114-A)
  - 200V 机器放电模型 (A115-A)
  - 1000V 充电器件模型 (C101)

2 应用

- I²C、SMBus、PMBus、MDIO、UART、低速 SDIO、GPIO 和其他双信号接口
- 汽车音响主机
- 汽车仪表组
- 汽车驾驶辅助摄像头

3 说明

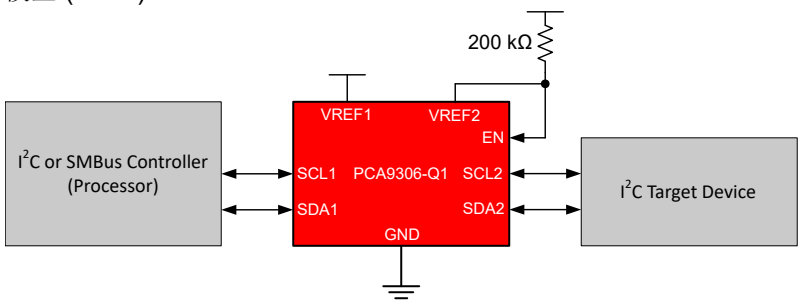
这款采用使能 (EN) 输入的双路双向 I²C 和 SMBus 电压电平转换器可在 1.2V 至 3.3V V_{REF1} 和 1.8V 至 5.5V V_{REF2} 的范围内工作。

PCA9306-Q1 可以在 1.2V 到 5V 之间实现双向电压转换而无须使用方向引脚。此开关具有低导通状态电阻 (r_{on})，可以在最短传播延迟情况下建立连接。当 EN 为高电平时，转换器开关打开，并且 SCL1 和 SDA1 I/O 被分别连接至 SCL2 和 SDA2 I/O，从而实现端口间的双向数据流。当 EN 为低电平时，转换器开关关闭，在端口之间存在一个高阻态。

器件信息

器件型号	封装(1)	封装尺寸（标称值）
PCA9306-Q1	VSSOP (8)	2.30mm x 2.00mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



简化版应用示意图

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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision B (April 2016) to Revision C (April 2022) — **Page**

- 将提到 I^2C 的旧术语实例通篇更改为控制器和目标。 1
- 向说明 (续) 的第一段添加了*禁用*时的文本 3
- Changed the θ_{JA} MAX value from 227°C/W to 275°C/W in the Absolute Maximum Ratings 5
- Changed the Thermal Information table 5
- Changed the V_{IK} MIN value to -1.2 V and the MAX value to 0 V in the Electrical Characteristics table 6
- Changed the t_{PHL} MAX value at C_L = 15 pF from: 0.5 ns to: 0.75 ns in the Switching Characteristics: Translating Down, V_{IH} = 3.3 V 6
- Changed the t_{PHL} MAX value at C_L = 15 pF from: 0.5 ns to: 0.75 ns in the Switching Characteristics: Translating Down, V_{IH} = 2.5 V 6
- Added Note *Specified by design* to the Switching Characteristics: Translating Up, V_{IH} = 2.3 V 7
- Added Note *Specified by design* to the Switching Characteristics: Translating Up, V_{IH} = 1.5 V 7
- Changed figure "ON-Resistance vs. Input Voltage" for V_{EN} = 4.5V 7
- Added sections Definition of threshold voltage through Current Limiting Resistance on V_{REF2} 9

Changes from Revision A (March 2013) to Revision B (April 2016) — **Page**

- 添加了 *ESD 等级*表、*特性说明*部分、*器件功能模式*、*应用和实施*部分、*电源相关建议*部分、*布局*部分、*器件和文档支持*部分以及*机械、封装和可订购信息*部分 1

5 说明（续）

在 I^2C 应用中，400 pF 总线电容限值限制了器件数量和总线长度。使用 PCA9306-Q1 使系统设计人员能够在禁用时隔离总线的两半；因此，可容纳更多 I^2C 器件或支持更长的布线长度。

PCA9306-Q1 也可用于运行两条总线，一条工作频率为 400 kHz，另一条工作频率为 100 kHz。如果两条总线在不同的频率下运行且需要运行 400 kHz 的总线，则必须将 100 kHz 总线隔离。如果控制器在 400 kHz 下运行，由于中继器所带来的延迟，最大系统运行频率有可能低于 400 kHz。

所有通道都具有相同的电气特性，而且各输出间的电压偏差或传播延迟偏差非常小。这优于分立式晶体管电压转换解决方案，因为该开关采用对称构造。该转换器为低压器件提供了出色的 ESD 保护，同时也保护了抗 ESD 能力较差的器件。

6 Pin Configuration and Functions

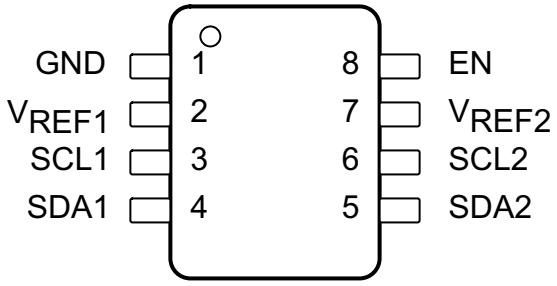


图 6-1. DCU Package, 8-Pin VSSOP, Top View

表 6-1. Pin Functions

PIN		DESCRIPTION
NO.	NAME	
1	GND	Ground, 0 V
2	V_{REF1}	Low-voltage-side reference supply voltage for SCL1 and SDA1
3	SCL1	Serial clock, low-voltage side. Connect to V_{REF1} through a pullup resistor.
4	SDA1	Serial data, low-voltage side. Connect to V_{REF1} through a pullup resistor.
5	SDA2	Serial data, high-voltage side. Connect to V_{REF2} through a pullup resistor.
6	SCL2	Serial clock, high-voltage side. Connect to V_{REF2} through a pullup resistor.
7	V_{REF2}	High-voltage-side reference supply voltage for SCL2 and SDA2
8	EN	Switch enable input. Connected to V_{REF2} and pulled up through a high resistor.

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{REF1}	DC reference voltage		– 0.5	7	V
V_{REF2}	DC reference bias voltage		– 0.5	7	V
V_I	Input voltage(2)		– 0.5	7	V
$V_{I/O}$	Input/output voltage(2)		– 0.5	7	V
	Continuous channel current			128	mA
I_{IK}	Input clamp current	$V_I < 0$		– 50	mA
θ_{JA}	Package thermal impedance			275.5	°C/W
T_{stg}	Storage temperature		– 65	150	°C

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) The input and input/output negative voltage ratings may be exceeded if the input and output current ratings are observed.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002(1)	±2000	V
		Charged-device model (CDM), per AEC Q100-011	±750	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

7.3 Recommended Operating Conditions

			MIN	MAX	UNIT
$V_{I/O}$	Input/output voltage	SCL1, SDA1, SCL2, SDA2	0	5	V
V_{REF1}	Reference voltage		0	5	V
V_{REF2}	Reference voltage		0	5	V
EN	Enable input voltage		0	5	V
I_{PASS}	Pass switch current			64	mA
T_A	Operating free-air temperature		– 40	105	°C

7.4 Thermal Information

THERMAL METRIC(1)		DCU (VSSOP)	UNIT
		8 PINS	
$R_{\theta JA}$ (2)	Junction-to-ambient thermal resistance	275.5	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	127.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	186.9	°C/W
ψ_{JT}	Junction-to-top characterization parameter	65.7	°C/W
ψ_{JB}	Junction-to-board characterization parameter	185.9	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.
(2) The package thermal impedance is calculated in accordance with JESD 51-7.

7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS			MIN	TYP(1)	MAX	UNIT
V_{IK}	Input clamp voltage		I_I = – 18 mA,	EN = 0 V		– 1.2		0	V
I_{IH}	Input leakage current		V_I = 5 V,	EN = 0 V				5	μA
C_i(EN)	Input capacitance		V_I = 3 V or 0 V				11		pF
$C_{io(off)}$	Off capacitance	SCLn, SDAn	V_O = 3 V or 0 V,	EN = 0 V			4	6	pF
$C_{io(on)}$	On capacitance	SCLn, SDAn	V_O = 3 V or 0 V,	EN = 3 V			10.5	12.5	pF
r_{on} (2)	ON-state resistance	SCLn, SDAn	V_I = 0 V,	I_O = 64 mA	EN = 4.5 V		3.5	5.5	Ω
					EN = 3 V		4.7	7	
					EN = 2.3 V		6.3	9.5	
					EN = 1.5 V		25.5	32	
			V_I = 2.4 V,	I_O = 15 mA	EN = 4.5 V	1	6	15	
					EN = 3 V	20	60	140	
			V_I = 1.7 V,	I_O = 15 mA	EN = 2.3 V	20	60	140	

(1) All typical values are at T_A = 25°C.
(2) Measured by the voltage drop between the SCL1 and SCL2, or SDA1 and SDA2 terminals, at the indicated current through the switch. ON-state resistance is determined by the lowest voltage of the two terminals.

7.6 Switching Characteristics: Translating Down, V_{IH} = 3.3 V

over recommended operating free-air temperature range, EN = 3.3 V, V_{IH} = 3.3 V, V_{IL} = 0, and V_M = 1.15 V (unless otherwise noted) (see 图 8-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
t_{PLH}	SCL2 or SDA2	SCL1 or SDA1	C_L = 50 pF		0.8	ns
			C_L = 30 pF		0.6	
			C_L = 15 pF		0.3	
t_{PHL}	SCL2 or SDA2	SCL1 or SDA1	C_L = 50 pF		1.2	ns
			C_L = 30 pF		1	
			C_L = 15 pF		0.75	

7.7 Switching Characteristics: Translating Down, V_{IH} = 2.5 V

over recommended operating free-air temperature range, EN = 2.5 V, V_{IH} = 2.5 V, V_{IL} = 0, and V_M = 0.75 V (unless otherwise noted) (see 图 8-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
t_{PLH}	SCL2 or SDA2	SCL1 or SDA1	C_L = 50 pF		1	ns
			C_L = 30 pF		0.7	
			C_L = 15 pF		0.4	
t_{PHL}	SCL2 or SDA2	SCL1 or SDA1	C_L = 50 pF		1.3	ns
			C_L = 30 pF		1	
			C_L = 15 pF		0.75	

7.8 Switching Characteristics: Translating Up, V_{IH} = 2.3 V

over recommended operating free-air temperature range, EN = 3.3 V, V_{IH} = 2.3 V, V_{IL} = 0, V_T = 3.3 V, V_M = 1.15 V, and R_L = 300 Ω (unless otherwise noted) (see 图 8-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
t_{PLH}	SCL1 or SDA1	SCL2 or SDA2	C_L = 50 pF		0.9(1)	ns
			C_L = 30 pF		0.6(1)	
			C_L = 15 pF		0.4(1)	
t_{PHL}	SCL1 or SDA1	SCL2 or SDA2	C_L = 50 pF		1.4(1)	ns
			C_L = 30 pF		1.1(1)	
			C_L = 15 pF		0.7(1)	

(1) Specified by design

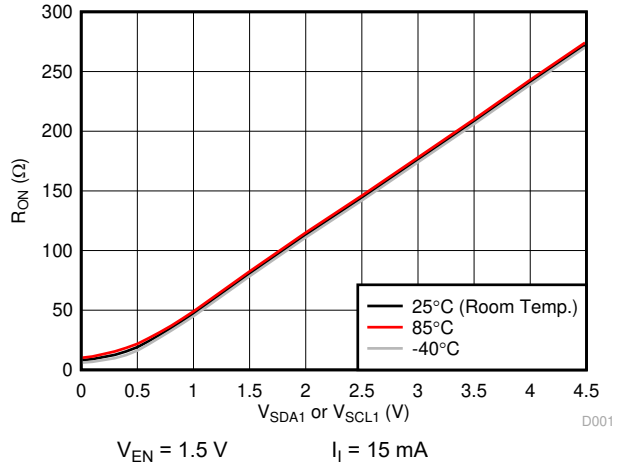
7.9 Switching Characteristics: Translating Up, V_{IH} = 1.5 V

over recommended operating free-air temperature range, EN = 2.5 V, V_{IH} = 1.5 V, V_{IL} = 0, V_T = 2.5 V, V_M = 0.75 V, and R_L = 300 Ω (unless otherwise noted) (see 图 8-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
t_{PLH}	SCL1 or SDA1	SCL2 or SDA2	C_L = 50 pF		1(1)	ns
			C_L = 30 pF		0.6(1)	
			C_L = 15 pF		0.4(1)	
t_{PHL}	SCL1 or SDA1	SCL2 or SDA2	C_L = 50 pF		1.3(1)	ns
			C_L = 30 pF		1.3(1)	
			C_L = 15 pF		0.8(1)	

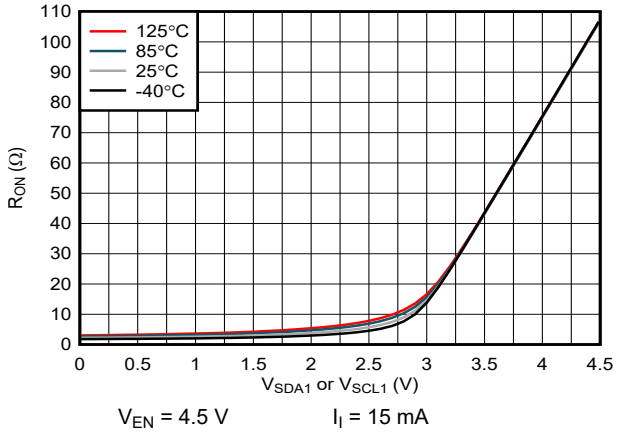
(1) Specified by design

7.10 Typical Characteristics



V_{EN} = 1.5 V I_I = 15 mA

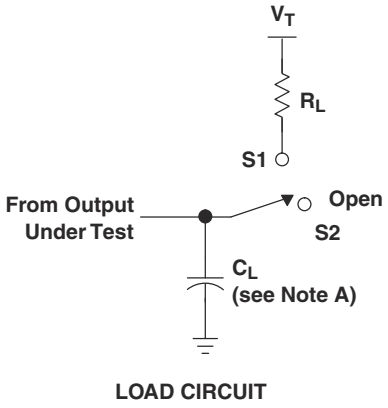
图 7-1. ON-Resistance (R_{ON}) vs Input Voltage (V_{SDA1} or V_{SCL1})



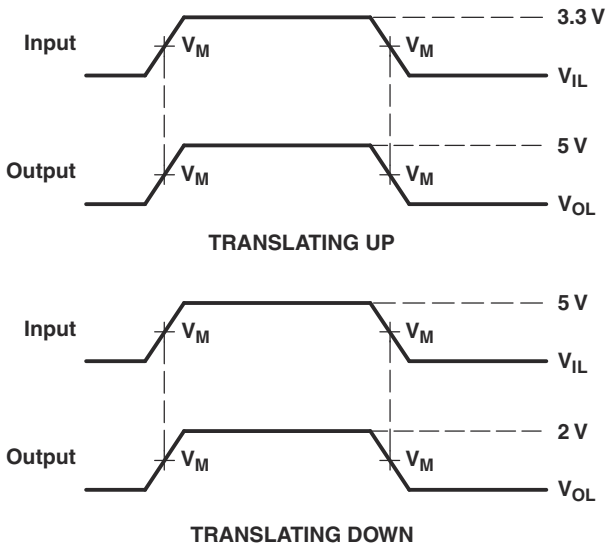
V_{EN} = 4.5 V I_I = 15 mA

图 7-2. ON-Resistance (R_{ON}) vs Input Voltage (V_{SDA1} or V_{SCL1})

8 Parameter Measurement Information



USAGE	SWITCH
Translating up	S1
Translating down	S2



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2 ns, t_f ≤ 2 ns.
C. The outputs are measured one at a time, with one transition per measurement.

图 8-1. Load Circuit for Outputs

9 Detailed Description

9.1 Overview

The PCA9306-Q1 is a dual bidirectional I^2C and SMBus voltage-level translator with an enable (EN) input that operates without the use of a direction pin. The voltage supply range for VREF1 is 1.2 V to 3.3 V and the supply range for VREF2 is 1.8 V to 5.5 V.

The PCA9306-Q1 can also be used to run two buses, one at a 400-kHz operating frequency and the other at a 100-kHz operating frequency. If the two buses are operating at different frequencies, the 100-kHz bus must be isolated by using the EN pin when the 400-kHz operation of the main bus is required. If the controller is running at 400 kHz, the maximum system operating frequency may be less than 400 kHz because of the delays added by the repeater.

In I^2C applications, the bus capacitance limit of 400 pF restricts the number of devices and bus length. The capacitive load on both sides of the PCA9306-Q1 must be considered when approximating the total load of the system, ensuring the sum of both sides is under 400 pF.

Both the SDA and SCL channels of the PCA9306-Q1 have the same electrical characteristics and there is minimal deviation from one output to another in voltage or propagation delay. This characteristic is a benefit over discrete transistor voltage translation solutions, because the fabrication of the switch is symmetrical. The translator provides excellent ESD protection to lower-voltage devices and at the same time protects less ESD-resistant devices.

9.1.1 Definition of threshold voltage

This document references a threshold voltage denoted as V_{th}, which appears multiple times throughout this document when discussing the NFET between V_{REF1} and V_{REF2}. The value of V_{th} is approximately 0.6 V at room temperature.

9.1.2 Correct Device Set Up

In a normal set up shown in 图 9-1, the enable pin and V_{REF2} are shorted together and tied to a 200-kΩ resistor, and a reference voltage equal to V_{REF1} plus the FET threshold voltage is established. This reference voltage is used to help pass lows from one side to another more effectively while still separating the different pull up voltages on both sides.

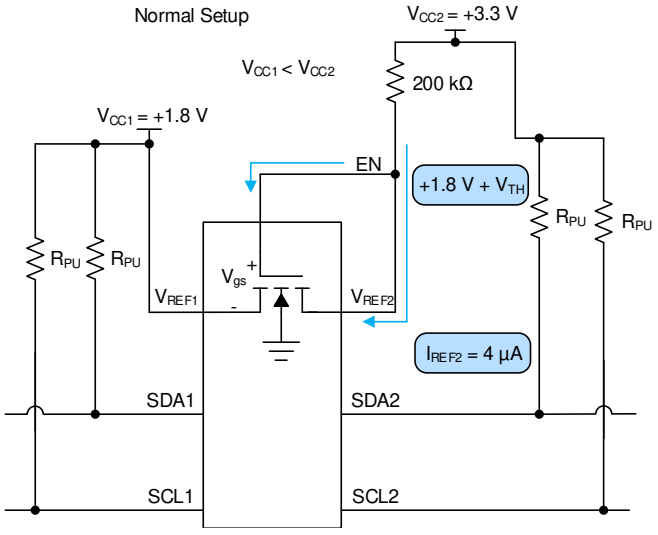


图 9-1. Normal Setup

Care should be taken to ensure V_{REF2} has an external resistor tied between it and V_{CC2}. If V_{REF2} is tied directly to the V_{CC2} rail without a resistor, then there is no external resistance from the V_{CC2} to V_{CC1} to limit the current such as in 图 9-2. This effectively looks like a low impedance path for current to travel through and potentially

break the pass FET if the current flowing through the pass FET is larger than the absolute maximum continuous channel current specified in section 6.1. The continuous channel current is larger with a higher voltage difference between V_{CC1} and V_{CC2}.

图 9-2 shows an improper set up. If V_{CC2} is larger than V_{CC1} but less than V_{th}, the impedance between V_{CC1} and V_{CC2} is high resulting in a low drain to source current, which does not cause damage to the device. Concern arises when V_{CC2} becomes larger than V_{CC1} by V_{th}. During this event, the NFET turns on and begin to conduct current. This current is dependent on the gate to source voltage and drain to source voltage.

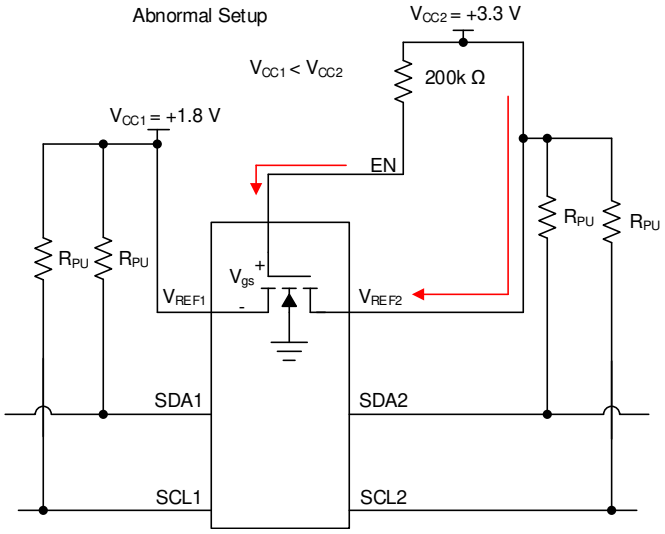


图 9-2. Abnormal Setup

9.1.3 Disconnecting a Target from the Main I2C Bus Using the EN Pin

PCA9306-Q1 can be used as a switch to disconnect one side of the device from the main I2C bus. This can be advantageous in multiple situations. One instance of this situation is if there are devices on the I2C bus which only supports fast mode (400 kHz) while other devices on the bus support fast mode plus (1 MHz). An example of this is displayed in 图 9-3.

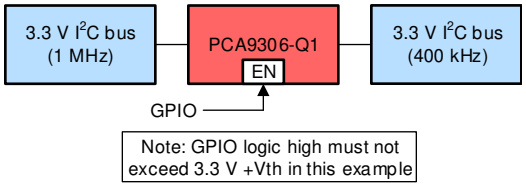


图 9-3. Example of an I2C bus with multiple supported frequencies

In this situation, if the controller is on the 1 MHz side then communicating at 1 MHz should not be attempted if PCA9306-Q1 were enabled. It needs to be disabled for PCA9306-Q1 to avoid possibly glitching state machines in devices which were designed to operate correctly at 400 kHz or slower. When PCA9306-Q1 is disabled, the controller can communicate with the 1 MHz devices without disturbing the 400 kHz bus. When the PCA9306-Q1 is enabled, communication across both sides at 400 kHz is acceptable.

9.1.4 Supporting Remote Board Insertion to Backplane with PCA9306-Q1

Another situation where PCA9306-Q1 is advantageous when using its enable feature is when a remote board with I2C lines needs to be attached to a main board (backplane) with an I2C bus such as in 图 9-4. If connecting a remote board to a backplane is not done properly, the connection could result in data corruption during a transaction or the insertion could generate an unintended pulse on the SCL line. Which could glitch an I2C device state machine causing the I2C bus to get stuck.

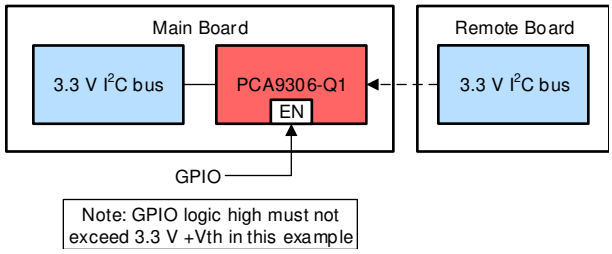


图 9-4. An example of connecting a remote board to a main board (backplane)

PCA9306-Q1 can be used to support this application because it can be disabled while making the connection. Then it is enabled once the remote board is powered on and the buses on both sides are IDLE.

9.1.5 Switch Configuration

PCA9306-Q1 has the capability of being used with its V_{REF1} voltage equal to V_{REF2}. This essentially turns the device from a translator to a device which can be used as a switch, and in some situations this can be useful. The switch configuration is shown in 图 9-5 and translation mode is shown in 图 9-6.

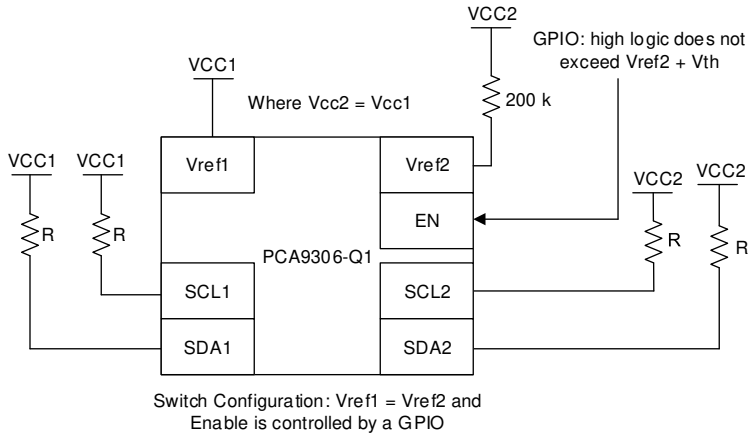


图 9-5. Switch Configuration

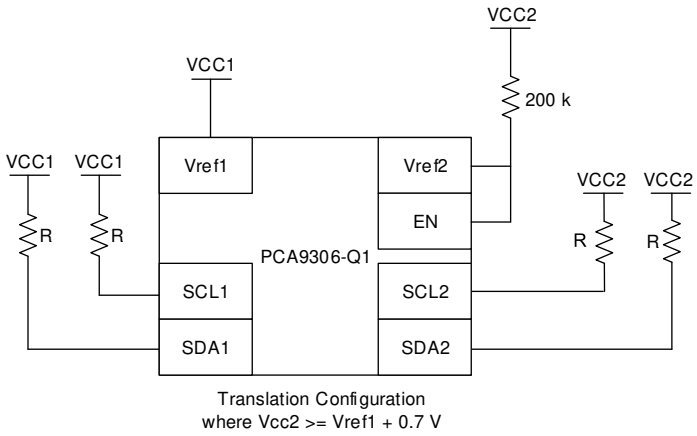


图 9-6. Translation Configuration

When PCA9306-Q1 is in the switch configuration (V_{REF1} = V_{REF2}), the propagation delays are different compared to the translator configuration. Taking a look at the propagation delays, if the pull up resistance and capacitance on both sides of the bus are equal, then in switch mode the PCA9306-Q1 has the same propagation delay from side one to two and side two to one. The propagation delays become lower when V_{CC1}/V_{CC2} is larger.

For example, the propagation delay at 1.8 V is longer than at 5 V in the switching configuration. When PCA9306-Q1 is in translation mode, side one propagate lows to side two faster than side two can propagate lows to side 1. This time difference increases as the difference between V_{CC2} and V_{CC1} becomes larger.

9.1.6 Controller on Side 1 or Side 2 of Device

I2C and SMBus are bidirectional protocol meaning devices on the bus can both transmit and receive data. PCA9306-Q1 was designed to allow for signals to be able to be transmitted from either side, thus allowing for the controller to be able to placed on either side of the device. 图 9-7 shows the controller on side two as opposed to the *Simplified Application Diagram* on page 1 of this data sheet.

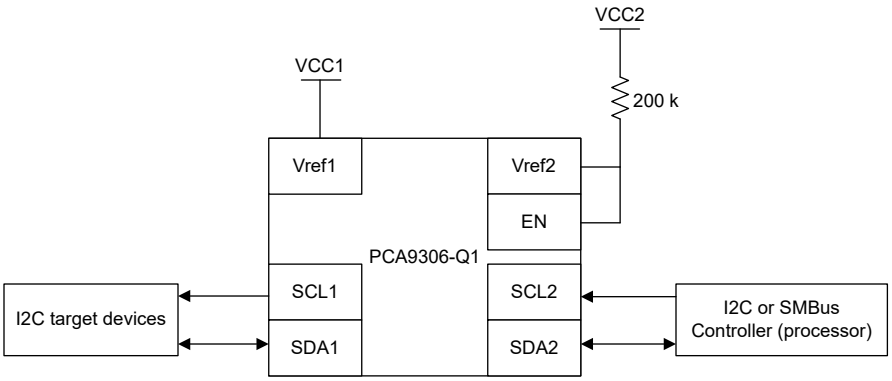


图 9-7. Controller on side 2 of PCA9306-Q1

9.1.7 LDO and PCA9306-Q1 Concerns

The V_{REF1} pin can be supplied by a low-dropout regulator (LDO), but in some cases the LDO can lose its regulation because of the bias current from V_{REF2} to V_{REF1}. If the LDO cannot sink the bias current, then the current has no other paths to ground and instead charges up the capacitance on the V_{REF1} node (both external and parasitic). This results in an increase in voltage on the V_{REF1} node. If no other paths for current to flow are established (such as back biasing of body diodes or clamping diodes through other devices on the V_{REF1} node), then the V_{REF1} voltage ends up stabilizing when V_{gs} of the pass FET is equal to V_{th}. This means V_{REF1} node voltage is V_{CC2} - V_{th}. Note that any target or controllers running off of the LDO now see the V_{CC2} - V_{th} voltage which may cause damage to those target or controllers if they are not rated to handle the increased voltage.

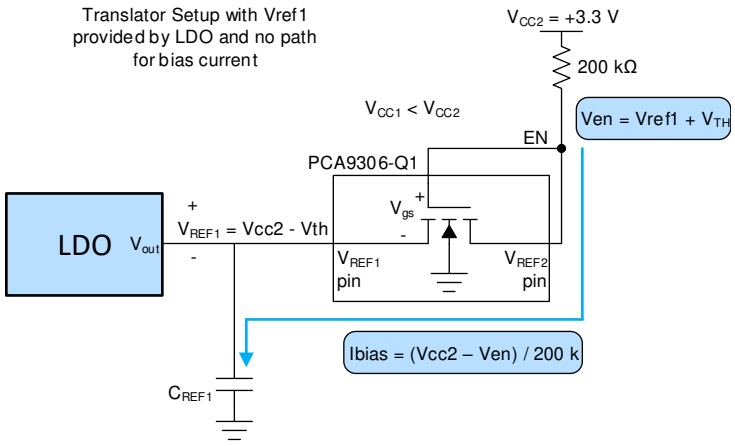


图 9-8. Example of no leakage current path when using LDO

To ensure LDO does not lose regulation due to the bias current of PCA9306-Q1, a weak pull down resistor can be placed on V_{REF1} to ground to provide a path for the bias current to travel. The recommended pull down resistor is calculated by 方程式 4 where 0.75 gives about 25% margin for error incase bias current increases during operation.

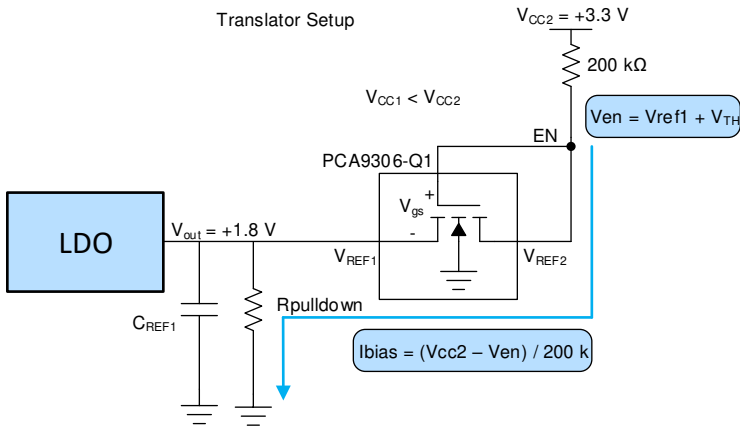


图 9-9. Example with Leakage current path when using an LDO

$$V_{en} = V_{REF1} + V_{th} \quad (1)$$

where

- V_{th} is approximately 0.6 V

$$I_{bias} = (V_{CC2} - V_{en})/200k \quad (2)$$

$$R_{pulldown} = V_{OUT}/I_{bias} \quad (3)$$

$$\text{Recommended } R_{pulldown} = R_{pulldown} \times 0.75 \quad (4)$$

9.1.8 Current Limiting Resistance on V_{REF2}

The resistor is used to limit the current between V_{REF2} and V_{REF1} (denoted as R_{CC}) and helps to establish the reference voltage on the enable pin. The 200k resistor can be changed to a lower value; however, the bias current proportionally increases as the resistor decreases.

$$I_{bias} = (V_{CC2} - V_{en})/R_{CC} : V_{en} = V_{REF1} + V_{th} \quad (5)$$

where

- V_{th} is approximately 0.6V

Keep in mind R_{CC} should not be sized low enough that I_{CC} exceeds the absolute maximum continuous channel current specified in section 6.1 which is described in 方程式 6.

$$R_{CC}(min) \geqslant (V_{CC2} - V_{en})/0.128 : V_{en} = V_{REF1} + V_{th} \quad (6)$$

where

- V_{th} is approximately 0.6V

9.2 Functional Block Diagram

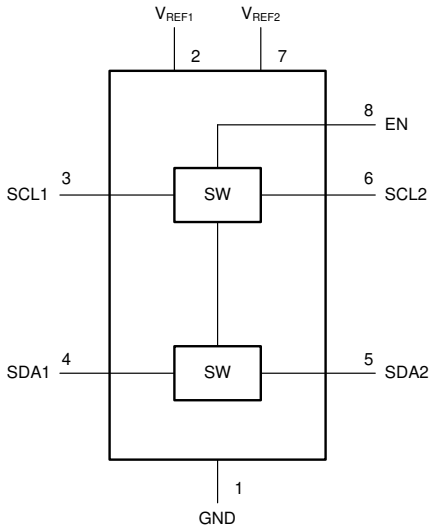


图 9-10. Logic Diagram (Positive Logic)

9.3 Feature Description

9.3.1 Enable (EN) Pin

The PCA9306-Q1 is a double-pole, single-throw switch in which the gate of the transistors is controlled by the voltage on the EN pin. In 图 10-1, the PCA9306-Q1 always remains enabled when power is applied to VREF2. 图 10-1, the device becomes enabled when a control signal from a processor is in a logic high state. In another variation, the EN pin can be controlled by the output of a processor, but VREF2 can be connected to a power supply through a 200-kΩ resistor. In this case, VREF2 and EN are not to be tied together and the SCL and SDA switches are in a high impedance state when EN is in a logic-low state, as shown in the 节 *9.4* section.

9.3.2 Voltage Translation

The primary feature of the PCA9306-Q1 is translating voltage from an I^2C bus referenced to VREF1 up to an I^2C bus referenced to VDPU, to which VREF2 is connected through a 200-kΩ pullup resistor. When translating a standard, open-drain I^2C bus, this is achieved by simply connecting pullup resistors from SCL1 and SDA1 to VREF1 and connecting pullup resistors from SCL2 and SDA2 to VDPU. Find more information on sizing the pullup resistors in the *Sizing Pullup Resistor* section.

9.4 Device Functional Modes

表 9-1 describes the two functions of the translation device.

表 9-1. Function Table

INPUT EN(1)	TRANSLATOR FUNCTION
H	SCL1 = SCL2, SDA1 = SDA2
L	Disconnect

(1) EN is controlled by the V_{REF2} logic levels and must be at least 1 V higher than V_{REF1} for best translator operation.

10 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客 户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

10.1 Application Information

10.1.1 General Applications of I^2C

As with the standard I^2C system, pullup resistors are required to provide the logic-high levels on the translator bus. The size of these pullup resistors depends on the system, but each side of the repeater must have a pullup resistor. The device is designed to work with standard-mode and fast-mode I^2C devices, in addition to SMBus devices. Standard-mode I^2C devices only specify 3 mA in a generic I^2C system where standard-mode devices and multiple controllers are possible. Under certain conditions, high termination currents can be used. When the SDA1 or SDA2 port is low, the clamp is in the ON state, and a low-resistance connection exists between the SDA1 and SDA2 ports. Assuming the higher voltage is on the SDA2 port when the SDA2 port is high, the voltage on the SDA1 port is limited to the voltage set by V_{REF1}. When the SDA1 port is high, the SDA2 port is pulled to the pullup supply voltage of the drain (V_{DPU}) by the pullup resistors. This functionality allows a seamless translation between higher and lower voltages selected by the user, without the need for directional control. The SCL1-SCL2 channel also functions in the same way as the SDA1-SDA2 channel.

10.2 Typical Application

图 10-1 and 图 10-2 show how these pullup resistors are connected in a typical application, as well as two options for connecting the EN pin.

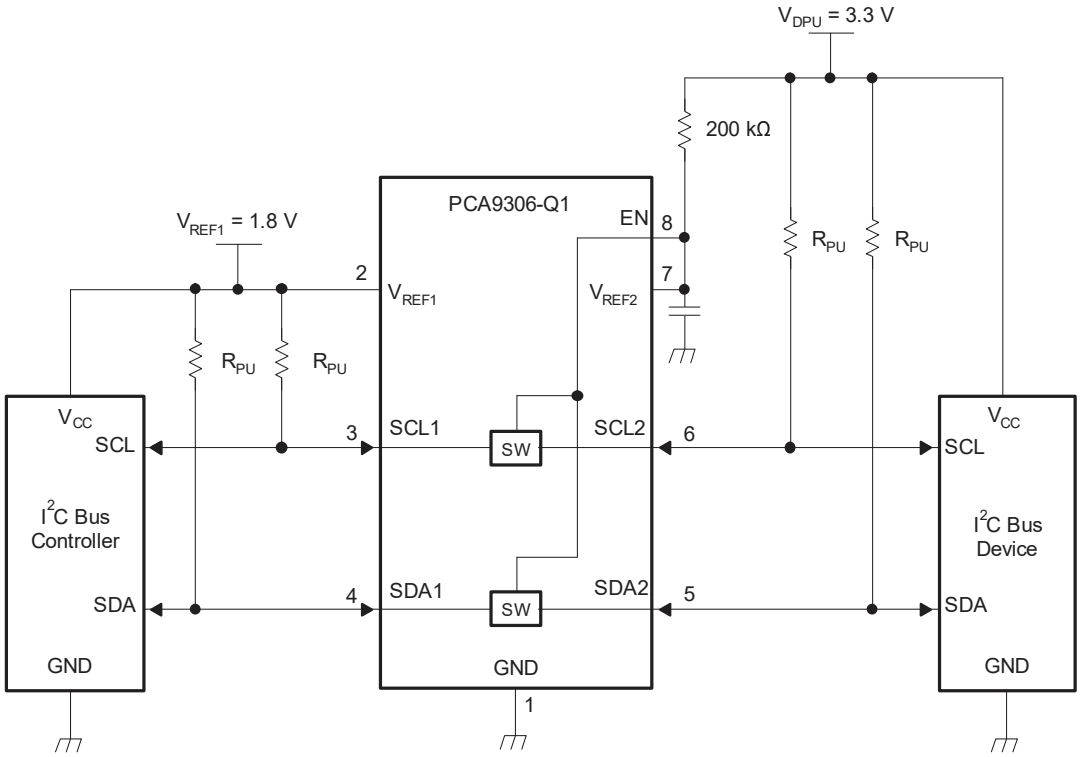


图 10-1. Typical Application Circuit (Switch Always Enabled) Diagram

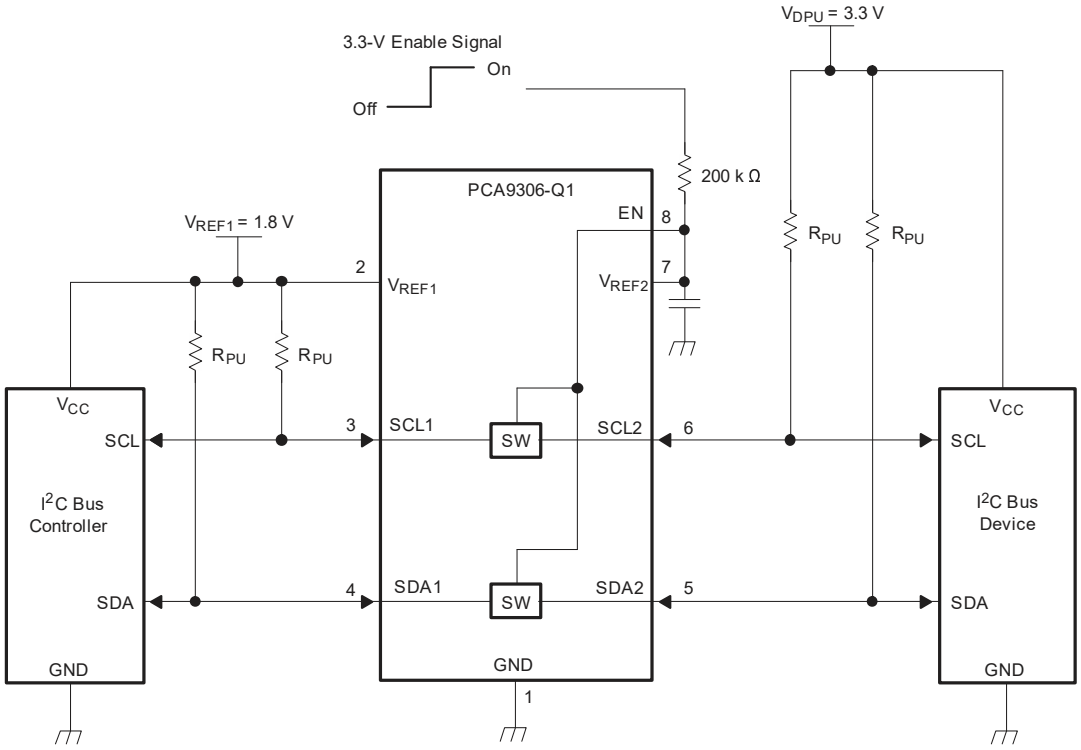


图 10-2. Typical Application Circuit (Switch Enable Control) Diagram

10.2.1 Design Requirements

表 10-1 lists the design parameters for this example.

表 10-1. Design Parameters

		MIN	TYP(1)	MAX	UNIT
V_{REF2}	Reference voltage	V_{REF1} + 0.6	2.1	5	V
EN	Enable input voltage	V_{REF1} + 0.6	2.1	5	V
V_{REF1}	Reference voltage	0	1.5	4.4	V
I_{PASS}	Pass switch current		14		mA
I_{REF}	Reference-transistor current		5		μA
T_A	Operating free-air temperature	–40		105	°C

(1) All typical values are at T_A = 25°C.

10.2.2 Detailed Design Procedure

10.2.2.1 Bidirectional Translation

For the bidirectional clamping configuration (higher voltage to lower voltage or lower voltage to higher voltage), the EN input must be connected to V_{REF2} and both pins pulled to high-side V_{DPU} through a pullup resistor (typically 200 kΩ). This allows V_{REF2} to regulate the EN input. A filter capacitor on V_{REF2} is recommended. The I^2C bus controller output can be totem-pole or open-drain (pullup resistors may be required) and the I^2C bus device output can be totem-pole or open-drain (pullup resistors are required to pull the SCL2 and SDA2 outputs to V_{DPU}). However, if either output is totem-pole, data must be unidirectional or the outputs must be 3-stateable and be controlled by some direction-control mechanism to prevent high-to-low contentions in either direction. If both outputs are open-drain, no direction control is needed.

The reference supply voltage (V_{REF1}) is connected to the processor core power-supply voltage.

10.2.2.2 Sizing Pullup Resistor

The pullup resistor value must limit the current through the pass transistor, when it is in the ON state, to about 15 mA. This ensures a pass voltage of 260 mV to 350 mV. If the current through the pass transistor is higher than 15 mA, the pass voltage also is higher in the ON state. To set the current through each pass transistor at 15 mA, the pullup resistor value is calculated as:

$$R_{PU} = \frac{V_{DPU} - 0.35\ V}{0.015\ A} \quad (7)$$

表 10-2 summarizes resistor values, reference voltages, and currents at 15 mA, 10 mA, and 3 mA. The resistor value shown in the +10% column (or a larger value) must be used to ensure that the pass voltage of the transistor is 350 mV or less. The external driver must be able to sink the total current from the resistors on both sides of the PCA9306-Q1 device at 0.175 V, although the 15 mA applies only to current flowing through the PCA9306-Q1 device.

表 10-2. Pullup Resistor Values

PULLUP RESISTOR VALUE (Ω)(1) (2)						
V_{DPU}	15 mA		10 mA		3 mA	
	NOMINAL	+10%(3)	NOMINAL	+10%(3)	NOMINAL	+10%(3)
5 V	310	341	465	512	1550	1705
3.3 V	197	217	295	325	983	1082
2.5 V	143	158	215	237	717	788
1.8 V	97	106	145	160	483	532
1.5 V	77	85	115	127	383	422
1.2 V	57	63	85	94	283	312

(1) Calculated for V_{OL} = 0.35 V
(2) Assumes output driver V_{OL} = 0.175 V at stated current
(3) +10% to compensate for V_{DD} range and resistor tolerance

10.2.2.3 PCA9306-Q1 Bandwidth

The maximum frequency of the PCA9306-Q1 device depends on the application. The device can operate at speeds of > 100 MHz given the correct conditions. The maximum frequency is dependent upon the loading of the application. The PCA9306-Q1 device behaves like a standard switch where the bandwidth of the device is dictated by the ON-resistance and ON-capacitance of the device.

图 10-5 shows a bandwidth measurement of the PCA9306-Q1 device using a two-port network analyzer.

The 3-dB point of the PCA9306-Q1 device is approximately 600 MHz. However, this is an analog type of measurement. For digital applications, the signal must not degrade up to the fifth harmonic of the digital signal. As a rule of thumb, the frequency bandwidth must be at least five times the maximum digital clock rate. This component of the signal is very important in determining the overall shape of the digital signal. In the case of the PCA9306-Q1 device, digital clock frequency of > 100 MHz can be achieved.

The PCA9306-Q1 device does not provide any drive capability like the PCA9515 or PCA9517 series of devices. Therefore, higher-frequency applications require higher drive strength from the host side. No pullup resistor is needed on the host side (3.3 V) if the PCA9306-Q1 device is being driven by standard CMOS push-pull output driver. Ideally, it is best to minimize the trace length from the PCA9306-Q1 device on the sink side (1.8 V) to minimize signal degradation.

You can then use a simple formula to compute the maximum *practical* frequency component or the *knee* frequency (f_{knee}). All fast edges have an infinite spectrum of frequency components. However, there is an inflection (or *knee*) in the frequency spectrum of fast edges where frequency components higher than f_{knee} are insignificant in determining the shape of the signal.

To calculate f_{knee}:

$$f_{knee} = 0.5 / RT\ (10 – 90\%) \quad (8)$$

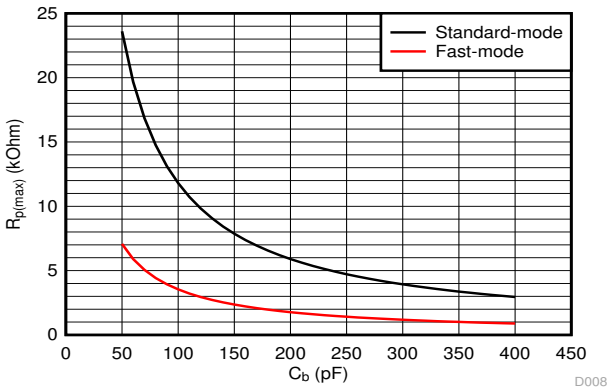
$$f_{knee} = 0.4 / RT\ (20 – 80\%) \quad (9)$$

For signals with rise-time characteristics based on 10- to 90-percent thresholds, f_{knee} is equal to 0.5 divided by the rise time of the signal. For signals with rise-time characteristics based on 20- to 80-percent thresholds, which is very common in many current device specifications, f_{knee} is equal to 0.4 divided by the rise time of the signal.

Some guidelines to follow that help maximize the performance of the device:

- Keep trace length to a minimum by placing the PCA9306-Q1 device close to the I^2C output of the processor.
- The trace length must be less than half the time of flight to reduce ringing and line reflections or non-monotonic behavior in the switching region.
- To reduce overshoots, a pullup resistor can be added on the 1.8-V side; be aware that a slower fall time is to be expected.

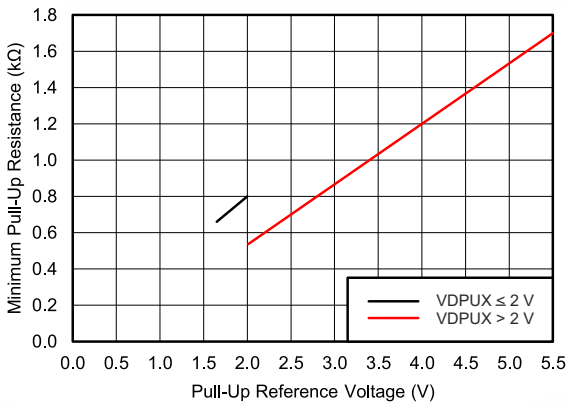
10.2.3 Application Curves



Standard mode (f_{SCL} = 100 kHz, t_r = 1 μs)

Fast mode (f_{SCL} = 400 kHz, t_r = 300 ns)

图 10-3. Maximum Pullup Resistance ($R_{p(max)}$) vs Bus Capacitance (C_b)



V_{OL} = 0.2 × V_{DPUX} , I_{OL} = 2 mA when V_{DPUX} ⩽ 2 V

V_{OL} = 0.4 V, I_{OL} = 3 mA when V_{DPUX} > 2 V

图 10-4. Minimum Pullup Resistance ($R_{p(min)}$) vs Pullup Reference Voltage (V_{DPUX})

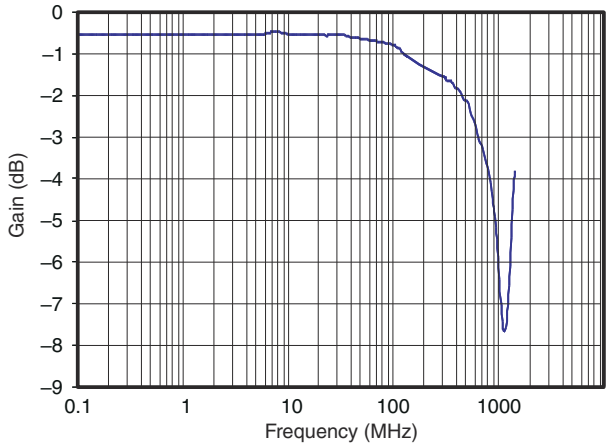


图 10-5. Bandwidth

11 Power Supply Recommendations

For supplying power to the PCA9306-Q1, the VREF1 pin can be connected directly to a power supply. The VREF2 pin must be connected to the VDPU power supply through a 200-kΩ resistor. Failure to have a high impedance resistor between VREF2 and VDPU results in excessive current draw and unreliable device operation.

12 Layout

12.1 Layout Guidelines

For printed-circuit board (PCB) layout of the PCA9306-Q1, common PCB layout practices must be followed; however, additional concerns related to high-speed data transfer such as matched impedances and differential pairs are not a concern for I^2C signal speeds.

In all PCB layouts, it is a best practice to avoid right angles in signal traces, to fan out signal traces away from each other upon leaving the vicinity of an integrated circuit (IC), and to use thicker trace widths to carry higher amounts of current that commonly pass through power and ground traces. The 100-pF filter capacitor must be placed as close to V_{REF2} as possible. A larger decoupling capacitor can also be used, but a longer time constant of two capacitors and the 200-kΩ resistor results in longer turnon and turnoff times for the PCA9306-Q1 device. These best practices are shown in 图 12-1.

For the layout example provided in 图 12-1, it would be possible to fabricate a PCB with only two layers by using the top layer for signal routing and the bottom layer as a split plane for power (V_{CC}) and ground (GND). However, a four-layer board is preferable for boards with higher-density signal routing. On a four-layer PCB, it is common to route signals on the top and bottom layer, dedicate one internal layer to a ground plane, and dedicate the other internal layer to a power plane. In a board layout using planes or split planes for power and ground, vias are placed directly next to the surface-mount component pad, which must attach to V_{CC} or GND, and the via is connected electrically to the internal layer or the other side of the board. Vias are also used when a signal trace must be routed to the opposite side of the board, but this technique is not demonstrated in 图 12-1.

12.2 Layout Example

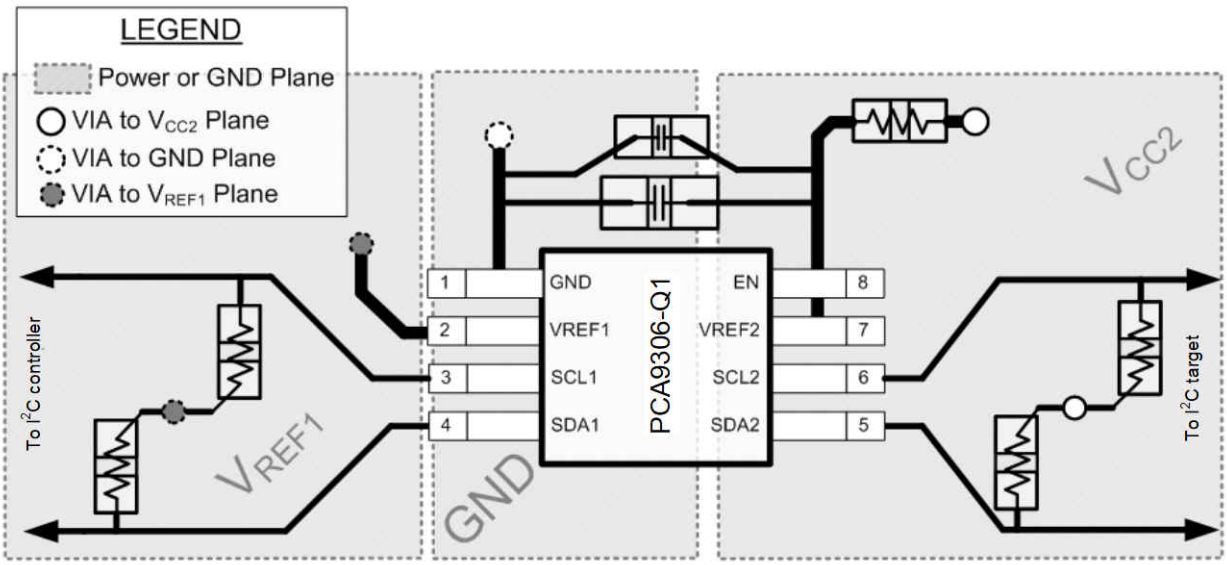


图 12-1. PCA9306-Q1 Layout Example

13 Device and Documentation Support

13.1 Documentation Support

13.1.1 Related Documentation

For related documentation, see the following:

Technical Documents – PCA9306-Q1 technical documents

13.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 *订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

13.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

13.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

13.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

13.6 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PCA9306IDCURQ1	ACTIVE	VSSOP	DCU	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	CCUS	Samples
PCA9306TDCURQ1	ACTIVE	VSSOP	DCU	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	YAAS	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF PCA9306-Q1 :

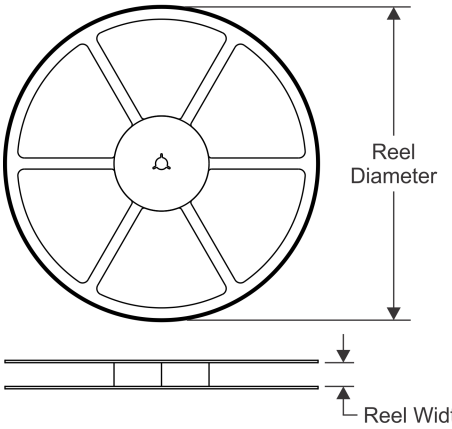
- Catalog : PCA9306

NOTE: Qualified Version Definitions:

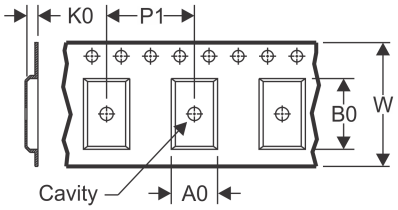
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

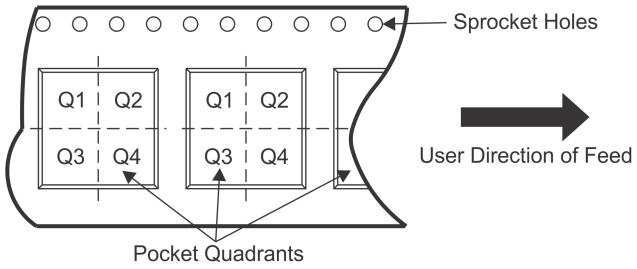


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

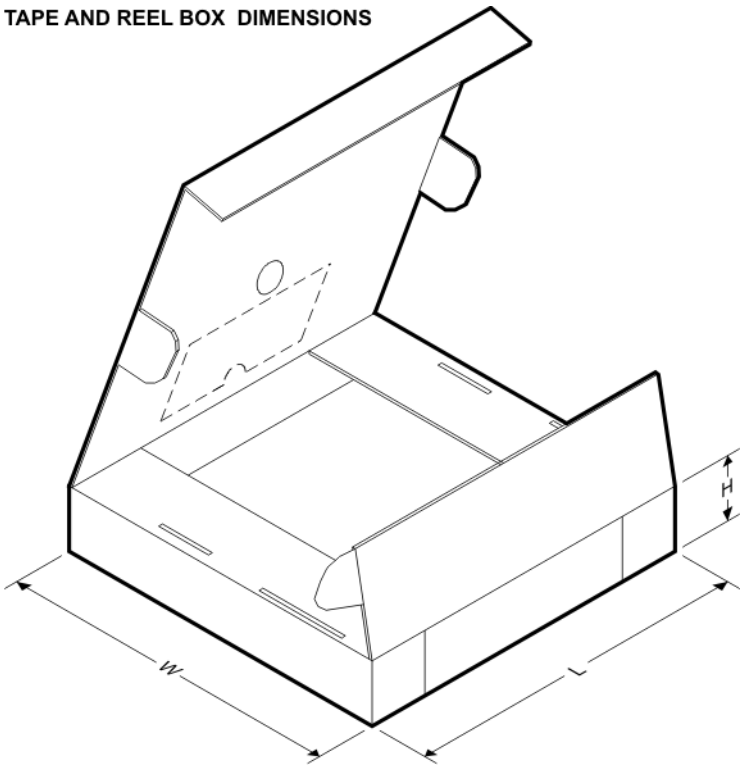
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PCA9306IDCURQ1	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
PCA9306TDCURQ1	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

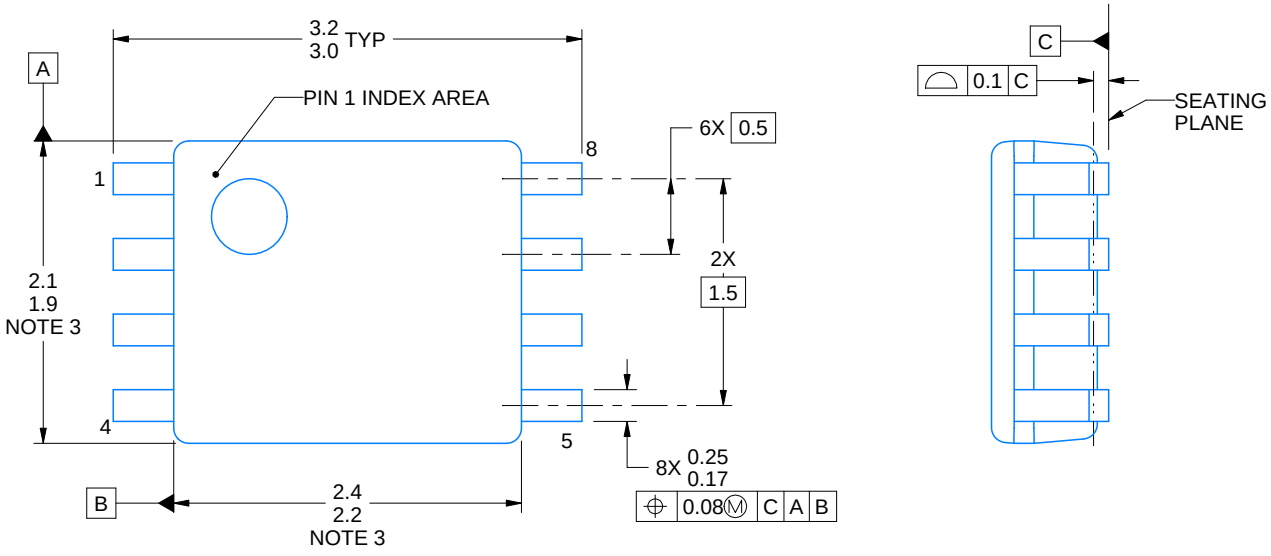
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PCA9306IDCURQ1	VSSOP	DCU	8	3000	202.0	201.0	28.0
PCA9306TDCURQ1	VSSOP	DCU	8	3000	202.0	201.0	28.0

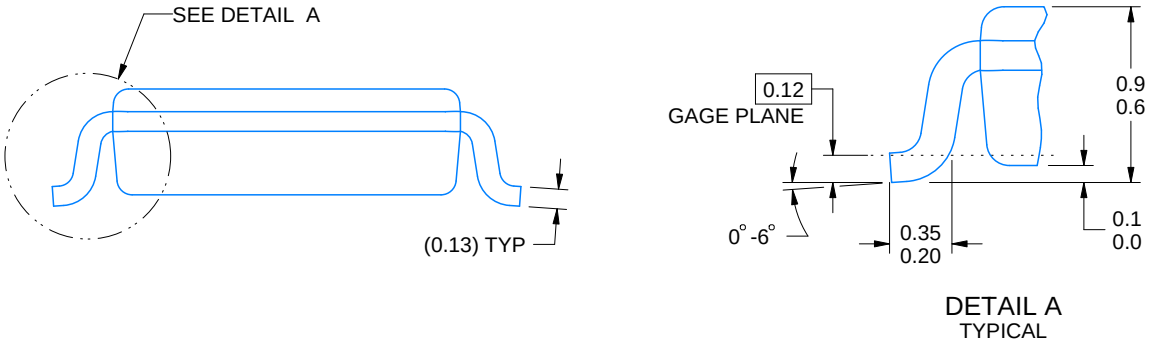
DCU0008A

PACKAGE OUTLINE

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE





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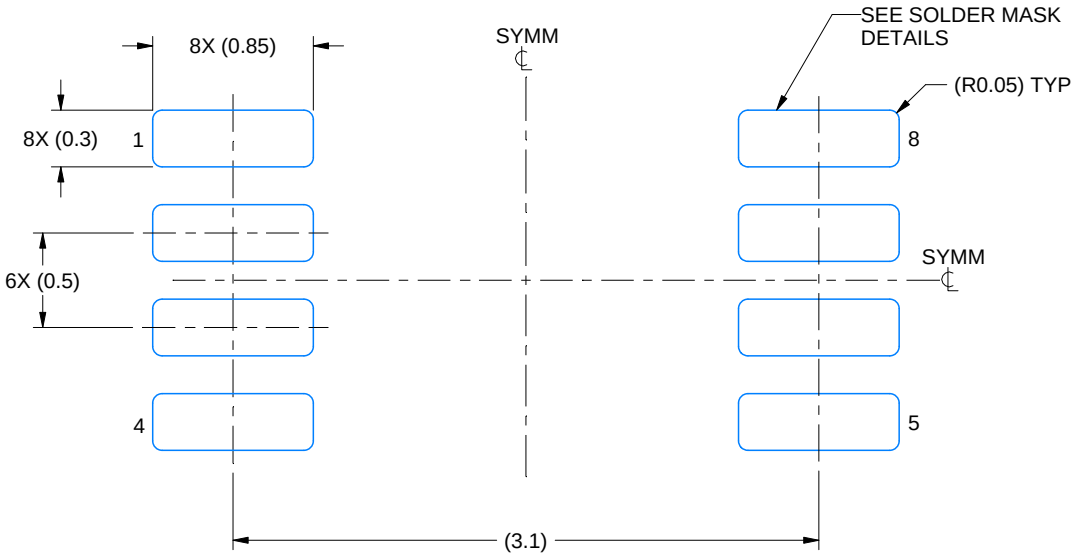
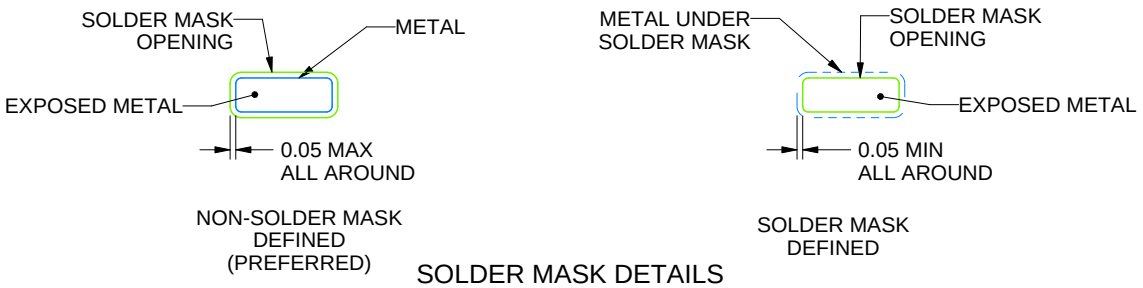
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-187 variation CA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 25X



SOLDER MASK DETAILS

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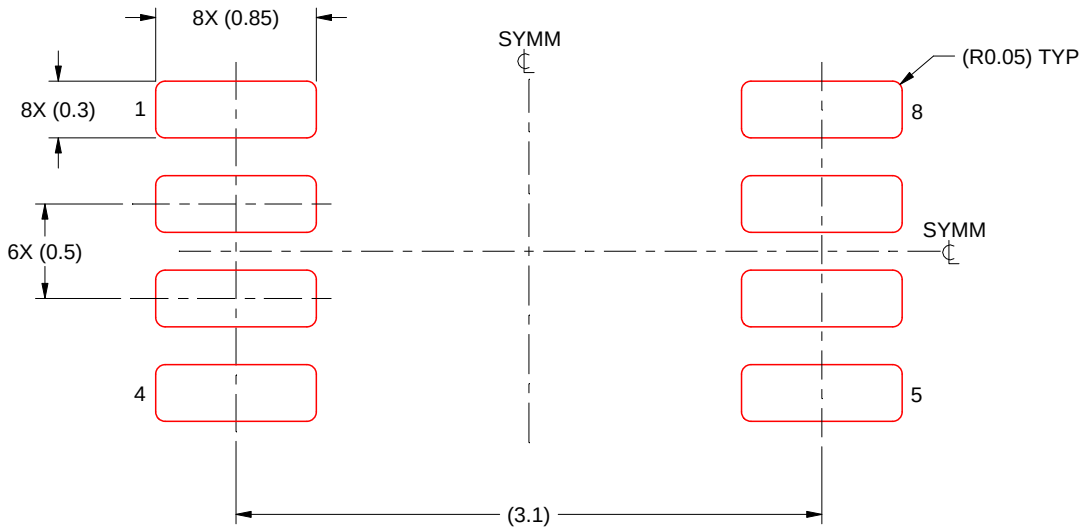
NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 25X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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